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IN THE CLAIMS:

Please cancel Claims 15, ~~16~~, ~~18~~, ~~22~~, ~~23~~ and ~~25~~ without prejudice or disclaimer of subject matter.

Please amend Claims 1 and 7, to read as follows. A marked-up copy of the amended claims, showing the changes made thereto, is attached.

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1. (Twice Amended) A solid-state image pickup device comprising:
- a substrate, provided with no wiring;
 - a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on said substrate;
 - a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip; and
 - a wiring substrate formed of a flexible material and connected electrically to said solid-state image pickup element chip,
- wherein a connection between said solid-state image pickup element chip and said wiring substrate is fixed only at a bump formed on an electrode pad, and
- wherein said substrate that is provided with no wiring has a thermal expansion coefficient substantially equal to that of said protection cap, and said substrate that is provided with no wiring and said protection cap are sealed with a sealing resin, so as to form a structure having a hollow space between said solid-state image pickup element chip and said protection cap.